

# STS200 Socket Series



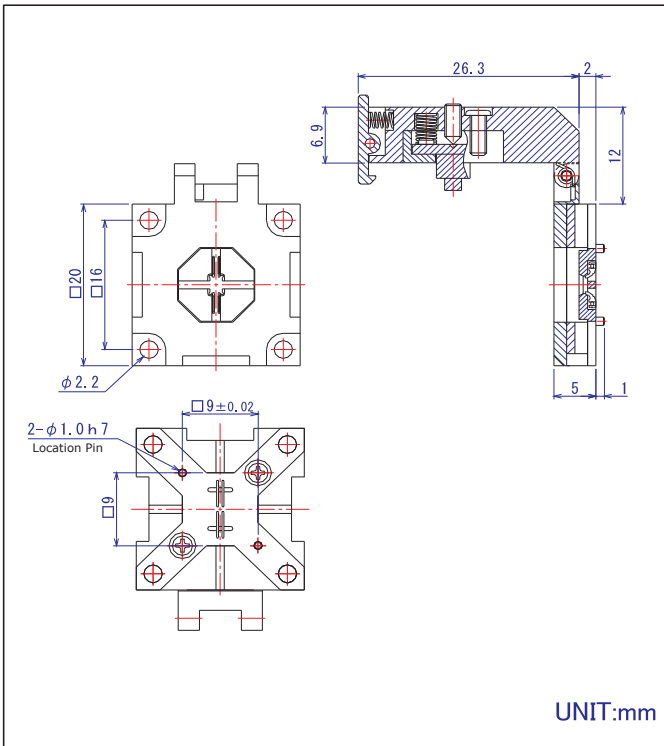
## PRODUCT DESCRIPTION

The new STS200 socket series provide a High RF small device package testing capability. Socket is designed as a simple maintenance structure with higher performance.

- Narrow pitch capable 0.3mm
- Quick delivery for custom package
- Various contacts available
- Small mounting area
- High carry current max 1A/pin
- High frequency device testing
- Burn-In testing

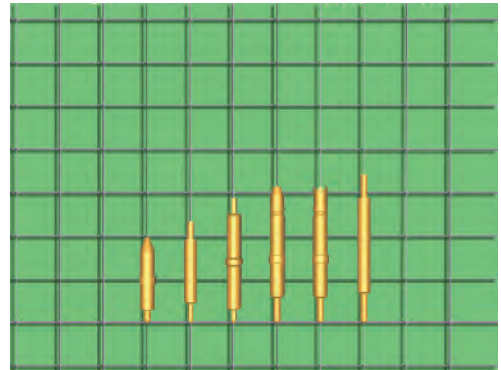
## SPECIFICATIONS

STS200 Socket Series		
Parameters	Unit	
<b>Physical properties</b>		
Maximum Package Size	mm x mm MAX	5 x 5
Housing Body Type	mm x mm	20 x 20 (standard)
Probe		L=2.0 to 3.2/L-contact*
Available Pitch	mm	0.3 to 0.8
Holding Type		Clam shell/One-touch/Fixed
Mechanical life	cycle	100,000
<b>Electrical properties</b>		
Contact Resistance	mΩ	100
Carry current	A	1
<b>Other</b>		
		RF device capable
		Capable for device contact sensor



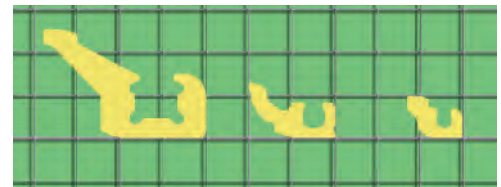
Applicable probes

scale: 1mm



Applicable L-Contact

scale: 1mm



\* see probe selections page for further details